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LAAS-CNRS Laboratoire d'Analyse et d'Architecture des Systèmes

Dry Etching of High [Al] AlGaAsSb Compounds Using Cl₂/N₂/Ar ICP RIE

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Context

Issue



GaSb based compound semiconductors emit in the mid-infrared range and present extremely good optoelectronic properties, with demonstrated bipolar laser diodes emitting from 2 to 3.5 µm with good performances. One key challenge remaining is the realization of high performance single mode emitters to enable - H2O the realization of efficient trace gas detection systems. Such diodes are often made with a core waveguide embedded in claddings made of AlGaAsSb with high Al content. Deep etching of high Al content claddings is known to be a particular challenge for deep etching with high aspect ratio, and restricts the designs achievable for laser diodes fabrication.

We present our work on deep etching of sub-micron 1D and 2D periodic structures designed to achieve DFB effect in edge emitting mid infrared lasers. DFB cavities can be realized using several geometries. We investigated two thoroughly opposite ones. The first studied geometry relies on periodic modulation of a waveguide width, and requires smooth etching of narrow 1D trenches with a mostly open etch mask. The other investigated geometry relies on 2D photonic crystal cavities, and requires deep etching of sub-micron diameter holes with high aspect ratios, in a mostly closed mask.

Towards the realization of side wall corrugated index coupled

distributed feedback GaSb based laser diode

Towards the realization of laser diodes all PhC electrically pumped in GaSb system

etching

Two 9 nm-thick QWs : Two 10 nm-thick $Ga_{0.34}In_{0.66}As_{0.11}Sb_{0.89}$ $QWs: GaIn_{0.34}As_{0.06}Sb$ Heterostructure AlGaAsSb / Heterostructure AlGaAsSb / $Ga_{0.75}Al_{0.25}As_{0.02}Sb_{0.98}$ Ga_{0.75}Al_{0.25}As_{0.027}Sb InGaAsSb for an emission around InGaAsSb for an emission around * * * $\downarrow \downarrow \downarrow \downarrow$ 2.3µm 2.3µm $Ga_{0.35}Al_{0.65}As_{0.05}Sb_0$ Ga_{0.10}Al_{0.9}As_{0.07}Sb_{0.93} GaSb GaAl_{0.9}AsSb GaAl_{0.65}AsSb GaSb 1500 100 1200 400 30 100 300 400 400 1500 100 300 100 1200 400 30 nm nm 1.5µm ■ 2nd order DFB laser Etching of submicron patterns with Feedback from corrugated high aspect ratio in the heterostructure : waveguide ➢ Characteristic Shallower etching dimensions : $\emptyset \sim 375$ Mesa Smooth sidewalls nm, Η ~ 3.5 μm Waveguide Smooth etched bottom ► Aspect ratio : 1:9 Cladding down **Previous work** System tool : SPTS ICP Omega201 **Realization of laser diodes all PhC electrically pumped in GaSb system Realization of side wall corrugated index coupled** distributed feedback GaSb based laser diode Masking strategy adopted Development of a multi-step etching process combining Cl_2/N_2 , O_2 and N_2 ICP plasma etching Transfer of ✤ Realization \sim O₂ oxydation Cl_2/N_2 SiO₂ 200 nm

of the grating

resist



Tri-layer mask used to open the submicron patterns in *III-V* substrate

Cr 50 nm

Photonic Crystals FIB *cut after complete* transfer in the mask

Cr 50 nm

« Masking strategy for all ICP-RIE etching of high aspect ratio Photonic Crystals in GaAs » A. Larrue, and al., JNTE (2008)

"Inductively coupled plasma etching of high aspect ratio twodimensional photonic crystals in Al-rich AlGaAs and AlGaAsSb" A. Larrue, and al., JVSTB Vol. 29(2), pp. 021006 (2011)



Photonic crystals etched in heterostructure AlGaAsInSb/AlGaAsSb

* * $P_{ICP} = 100W$

 \circ \circ $P_{ICP} = 50W$



Definition of the mesa by optical lithography

◆Dry etched with Cl2/N2/Ar ICP-RIE of the pattern through the top cladding. The etching is stopped on the top of the waveguide

Influence of Cl₂ ratio :

 $P_{ICP} = 75 \text{ W} - P_{bias} = 60 \text{ W} -$

the grating by



l'institut

d'électronique

Operating range :

 \clubsuit Gas : CHF₃, CF₄, O₂, Cl₂, N₂, Ar ✤RF plasma powers (13.56 MHz) : $P_{ICP} = \text{from 0 to 600 W}$ ***** RF bias power of the wafer : $P_{\text{bias}} = \text{from 0 to 100 W}$ Electrostatic chuck • Helium cooling : $-20^{\circ}C < T_{wafer} < 60^{\circ}C$ ✤ Pressure : from 2 to 50 mTorr

Optimization of the process of chlorinated ICP-RIE etching III-V materials

Influence of ICP power : $P_{\text{bias}} = 60 \text{ W} - \text{Pression} = 5.5 \text{ mTorr} - 100 \text{ mTorr}$ $Cl_2/N_2/Ar 45/15/5$ sccm



Influence of pressure : $P_{ICP} = 75 \text{ W} - P_{\text{bias}} = 60 \text{ W} Cl_2/N_2/Ar \, 45/15/5 \, sccm$

passivation



7.5

Deep etching process optimized : $Cl_2/N_2/Ar \, 45/15/5 \, sccm - 75 \, W \, ICP$ 60 W bias - 5.5 mTorr



 $Cl_2/N_2/Ar \ 45/15/5 \ sccm - 500 \ W \ ICP$ 60 W bias - 7,0 mTorr



Conclusion

Deep dry etching of shallow features in high Al content AlGaAsSb can be achieved using Cl2/N2/Ar chemistries. Good performances are achieved provided that the etching regime (ICP or RIE) is chosen in accordance with the designed geometry and aspect ratio, and devices with good opto-electrical performances were fabricated.

✓ Establishment of a high aspect ratio deep etching process of PhC in GaInAsSb/AlGaAsSb system ✓ Successful insertion of this technological step in a complete process

✓ Establishment of deep etching process of grating in GaInAsSb/AlGaAsSb system

✓ Successful insertion of this technological step in a complete process

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